ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC, Bannock	burn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a decla he declaratio	ration of t n encomp	the substance passes all low	es within ver level 1	the manufactur naterials for w	rer listed it hich the m	em. Note anufactur	: if the item is an rer has engineerin	assembly with low ng responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information														
Company name* Company unique ID			que ID	Unique ID Authority					Response Date*					
nsemi											2023-06-08			
Contact Name Title - Contact			et]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Enviro Compl			ro Compliance		NA			Product-Env-Stewards@onsemi.com						
Authorized Representative* Title - Representative			sentative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective D	ate Ver	rsion	Manufacturing Site		7	Weight*	UOM	Unit Type
	AR0237 0-DR	20237CSSC12SPRA 2MP 1/3 CIS SO				2023-06-08			TA1		2	264.22	mg	Each
Ianufacturing Proccess Informa	tion													
Terminal Plating / Grid Array Ma	aterial	Terminal Base A	erminal Base Alloy J-STD-02		L Rating	Peak P	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperat	ure Nur	nber of Reflow C	Cycles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn) CU Alloy			4		260		C	30		secon	ds 3			
omments												•		
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	57.0	mg		Misc.	proprietary data		0.2166	mg
			Supplier	Silicon (Si)	7440-21-3		56.2191	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5643	mg
Die Attach	2.5	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9375	mg
			Supplier	Ethylene Glycol	107-21-1		0.025	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.075	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.525	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9375	mg
Imaging Lens	60.5	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.025	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		3.025	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		3.025	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.025	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3025	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.025	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.025	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		42.0475	mg
Lid Attach	2.6	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.8216	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1352	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.8216	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.8216	mg
Mold Compound-Black	54.0	mg		Phenolic Resin	proprietary data		8.1	mg
			Supplier	Oxirane	39817-09-9		8.1	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.62	mg
			Supplier	Carbon Black (C)	1333-86-4		0.54	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.56	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.08	mg
Substrate and Solder Mask	87.4	mg	Supplier	Acetophenone	98-86-2		1.713	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		19.3941	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1449	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.1537	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2884	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2884	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4261	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.74	mg
			Supplier	Copper (Cu)	7440-50-8	42.389	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.8624	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5	0.22	mg